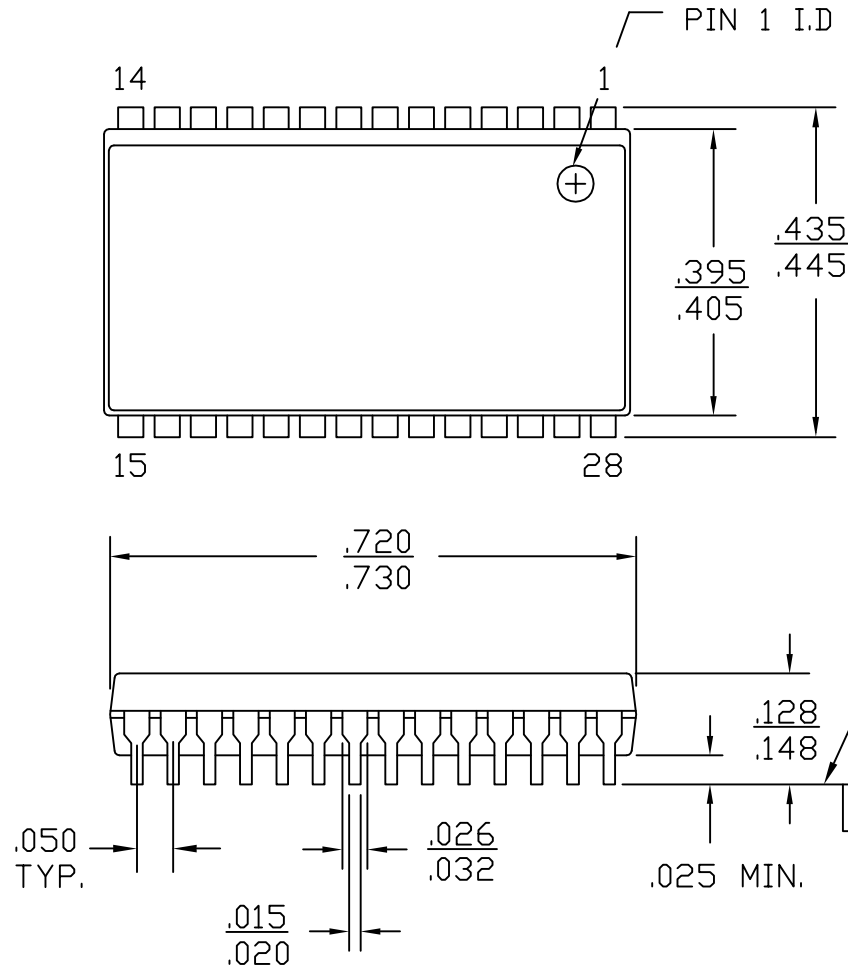
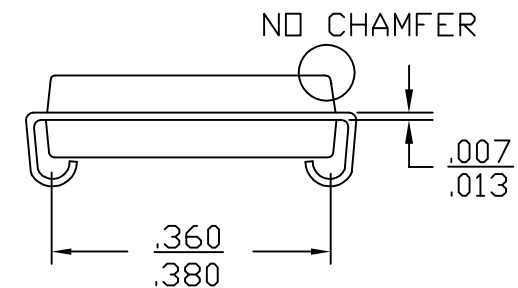


28 Lead (400 MIL) Molded SOJ V28

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	49389	CHG. TITLE	05/29/97	N/A
1	-	*B	60088	REMOVE DETAIL "A"	12/29/98	N/A
1	-	*C	2871406	Changed template, & title from 28LD (400 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 28L SOJ 400 MILS V28.4 (MOLDED SOJ V28).	02/02/10	QAD
1	-	*D	2887115	Removed chamfer on pin #1 corner	03/03/10	JVP
1	-	*E	3146953	ECN SUNSET NO CHANGE	01/19/11	QAD




DIMENSIONS IN INCHES MIN.
MAX.



NOTES :

1. PACKAGE WEIGHT : 1.24g
2. JEDEC REFERENCE : MS-027

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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°		DESIGNED BY	DATE	 CYPRESS Company Confidential			
		HTN	12/29/98				
		DRAWN BY	DATE	TITLE PACKAGE OUTLINE, 28L SOJ 400 MILS V28.4 (MOLDED SOJ V28)			
		HTN	12/29/98				
CHECKED BY	DATE	SIZE A PART NO. DWG NO REV					
TSV	02/02/10						
APPROVED BY	DATE	V28.4 51-85032 *E					
QAD	02/02/10						
MATERIAL	N/A	APPROVED BY	DATE	SCALED TO FIT		SHEET 1 OF 1	
FINISH	N/A	JGUA	02/02/10	N/A			
		N/A	N/A				